

Description

The SX180N03T uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS}=30V$ $I_D=180A$

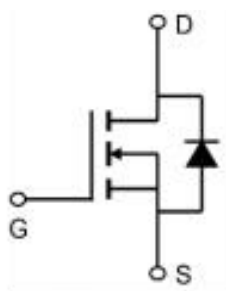
$R_{DS(ON)} < 3.2m\Omega$ @ $V_{GS}=10V$

Application

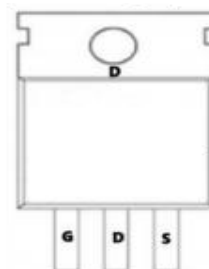
Battery protection

Load switch

Uninterruptible power supply



TO-263-3L



Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, V_{GS} @ 10V ^{1,6}	180	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, V_{GS} @ 10V ^{1,6}	145	A
I_{DM}	Pulsed Drain Current ²	500	A
EAS	Single Pulse Avalanche Energy ³	246	mJ
I_{AS}	Avalanche Current	70.2	A
$P_D@T_C=25^\circ C$	Total Power Dissipation ⁴	187	W
T_{STG}	Storage Temperature Range	-55 to 175	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 175	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	0.8	$^\circ C/W$

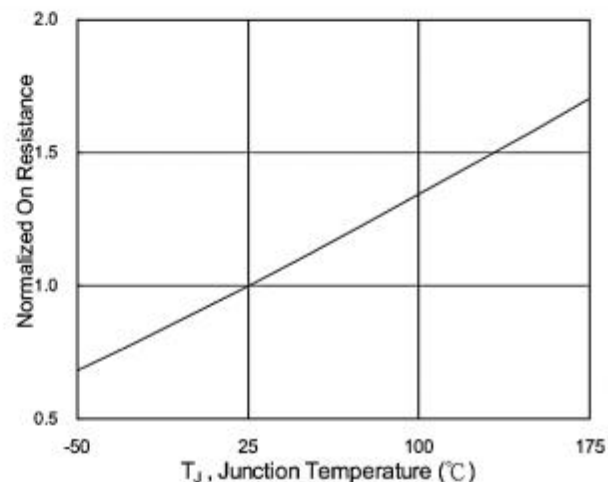
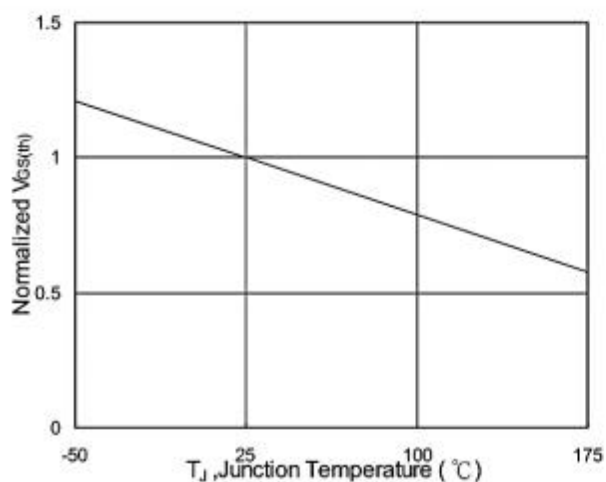
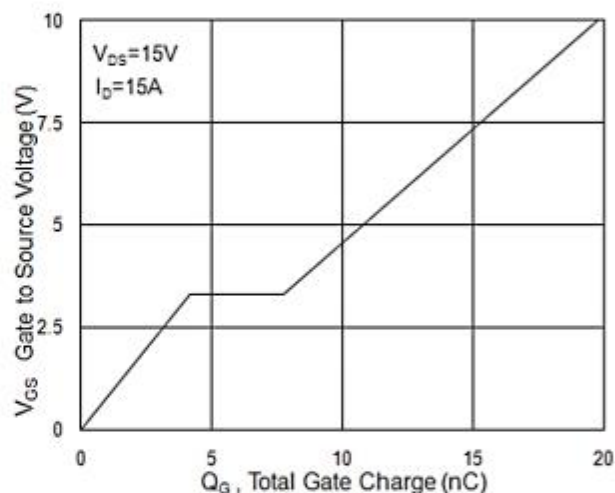
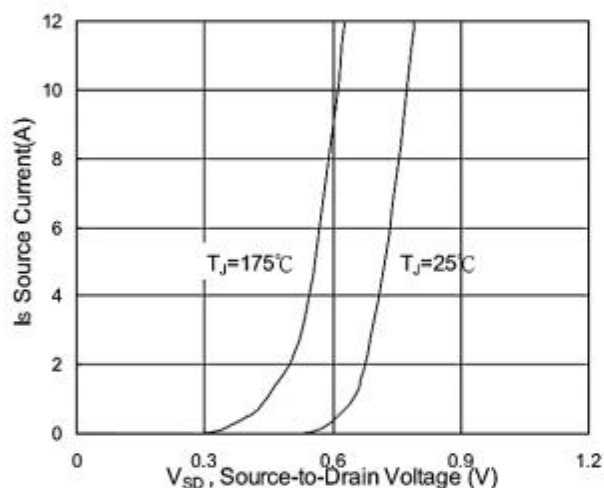
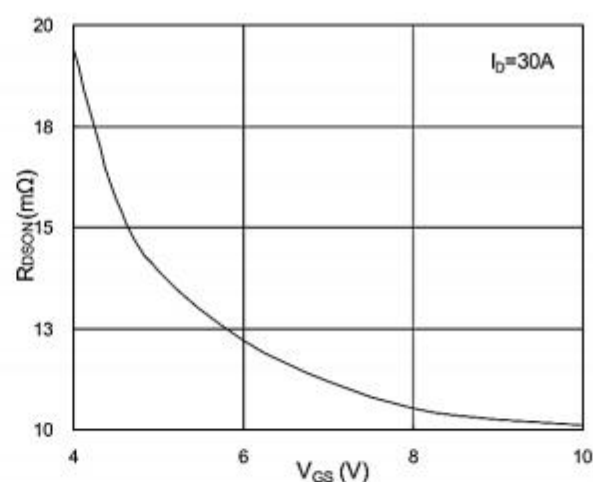
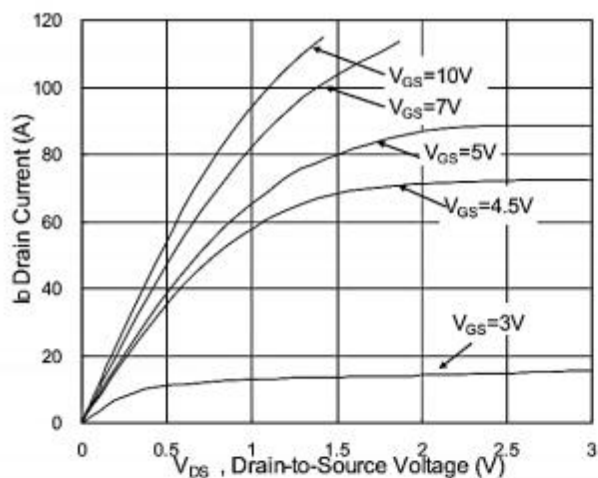
Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	30	38	---	V
ΔBVDSS/ΔT _J	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =1mA	---	0.014	---	V/°C
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =30A	---	2.1	3.2	mΩ
		V _{GS} =4.5V , I _D =15A	---	3.0	3.8	
VGS(th)	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.2	1.6	2.5	V
ΔVGS(th)	VGS(th) Temperature Coefficient		---	-4	---	mV/°C
IDSS	Drain-Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =25°C	---	---	1	uA
		V _{DS} =24V , V _{GS} =0V , T _J =55°C	---	---	5	
IGSS	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V	---	---	±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =30A	---	50	---	S
R _g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz	---	1.7	---	Ω
Q _g	Total Gate Charge (4.5V)	V _{DS} =15V , V _{GS} =10V , I _D =15A	---	56.9	---	nC
Q _{gs}	Gate-Source Charge		---	13.8	---	
Q _{gd}	Gate-Drain Charge		---	23.5	---	
Td(on)	Turn-On Delay Time	V _{DD} =15V , V _{GS} =10V R _G =3.3Ω, I _b =1A	---	20.1	---	ns
T _r	Rise Time		---	6.3	---	
Td(off)	Turn-Off Delay Time		---	124.6	---	
T _f	Fall Time		---	15.8	---	
Ciss	Input Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz	---	5850	---	pF
Coss	Output Capacitance		---	720	---	
Crss	Reverse Transfer Capacitance		---	525	---	
IS	Continuous Source Current ^{1,5}	V _G =V _D =0V , Force Current	---	---	205	A
ISM	Pulsed Source Current ^{2,5}		---	---	500	A
VSD	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C	---	---	1.2	V

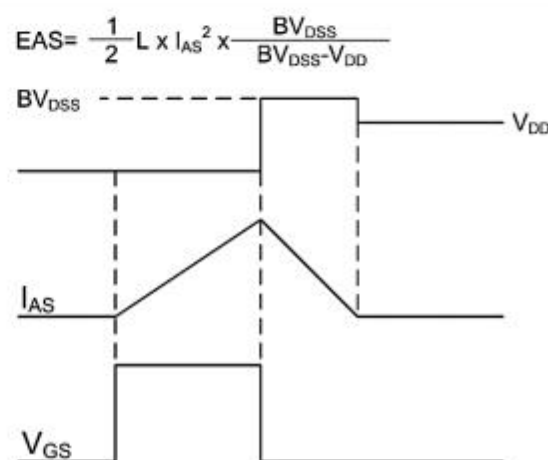
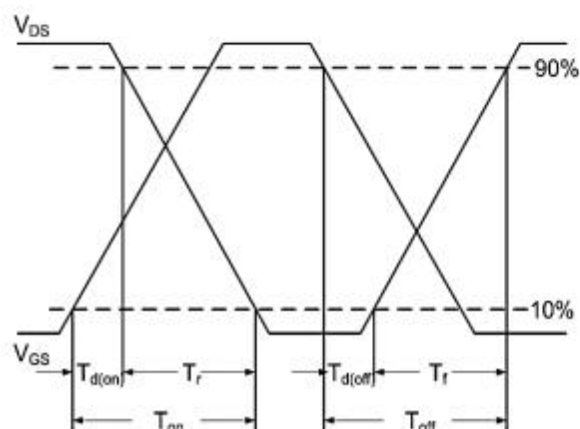
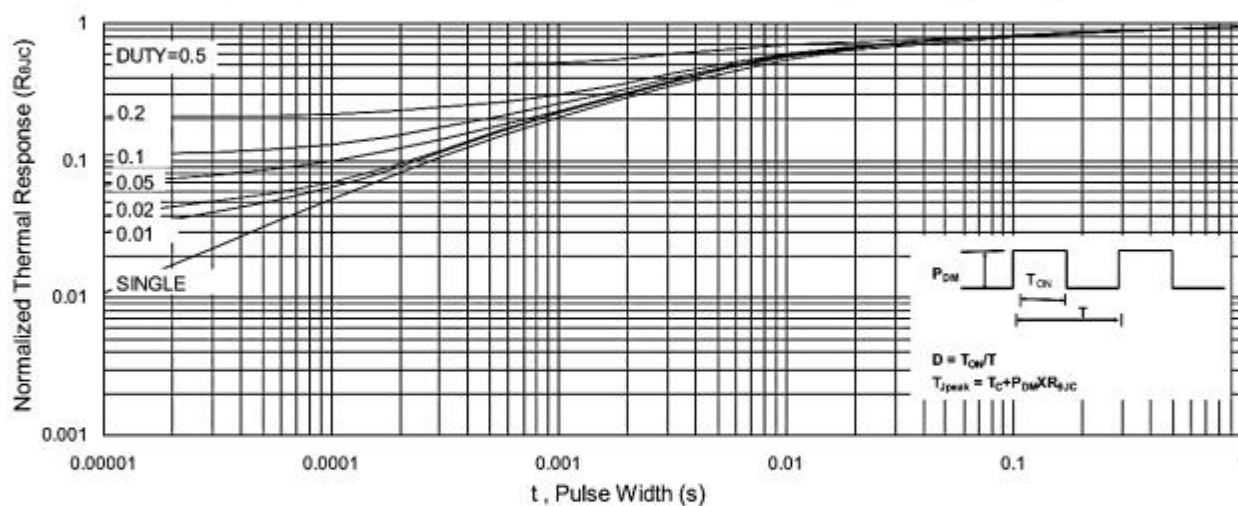
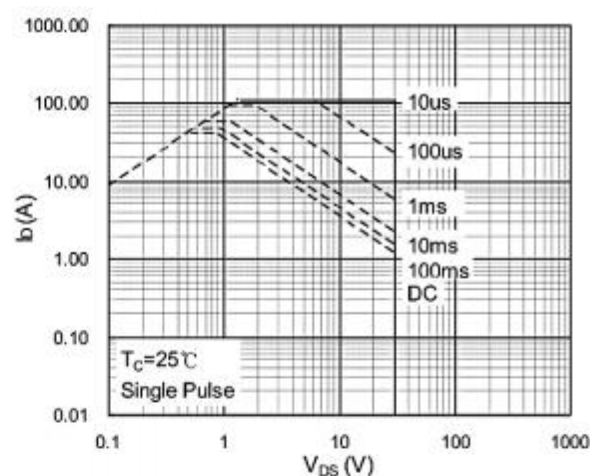
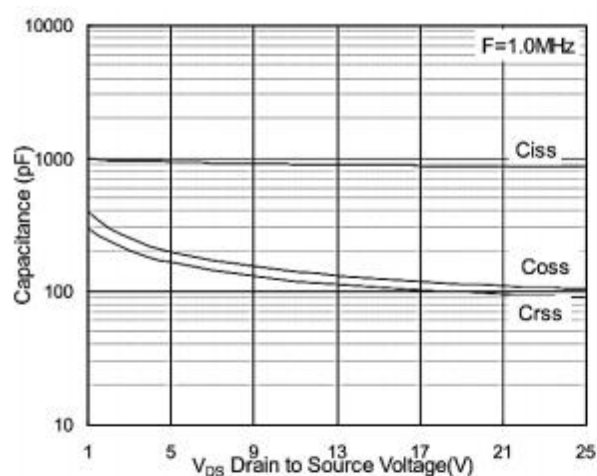
Note :

- 1、The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
- 2、The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3、The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1Mh,IAS=22A
- 4、The power dissipation is limited by 175°C junction temperature
- 5、The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

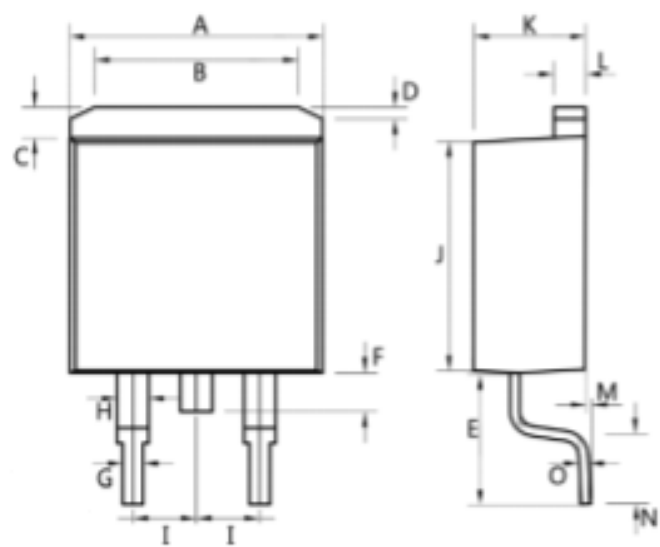
Typical Characteristics



Typical Characteristics



Package Mechanical Data- TO-263-3L



Dim.	Min.	Max.
A	10.0	10.5
B	7.25	7.75
C	1.3	1.5
D	0.55	0.75
E	5.0	6.0
F	1.4	1.6
G	0.75	0.95
H	1.15	1.35
I	Typ 2.54	
J	8.4	8.6
K	4.4	4.6
L	1.25	1.45
M	0.02	0.1
N	2.4	2.8
O	0.35	0.45
All Dimensions in millimeter		

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
TAPING	TO-263-3L		800